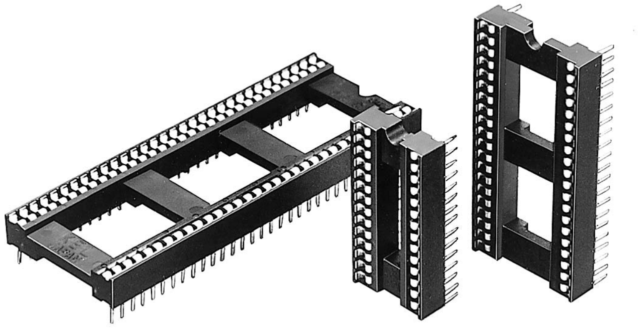
SIC01 SERIES
70mil (1.778mm) SHRINK IC SOCKET



SUMMARY

As IC electronic packaging progresses towards further LSI/VLSI technology, KEL Corp. has met this challenge by developing a new 70mil Shrink IC socket.

Kel has again incorporated a high reliability and quality design also available in the first generation (ICC05 Socket)

FEATURES

- Double beam stamped and formed contacts
- Up to 50% saving on PCB real estate
- Closed bottom design to prevent solder wicking
- Low profile design
- Anti-wicking sealant available
- RoHS compliance

SPECIFICATIONS

- Current rating : 1A per contact
- Contact resistance : 20mΩ max.
- Dielectric withstanding voltage : 800V AC for 1minute
- Insulation resistance : 5,000MΩmin. at 500V DC
- Insertion force : 454g max./pin
- Withdrawal force : 14.17g max./pin
- Operating temperature : -20°C~+70°C

ORDER CODE

SIC01-□□□-361T□-F

- F : RoHS Compliance
- T : Standard
  TP : Epoxy sealant
- Contact
- No. of contacts
  028 : 28pin 056 : 56pin
  040 : 40pin 064 : 64pin
  042 : 42pin
- Series name

SIC01-064-361G

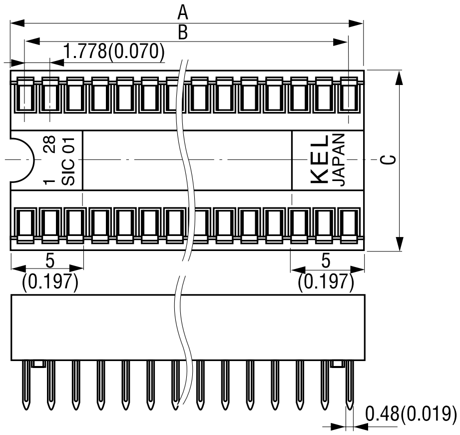
- G : RoHS Compliance

MATERIAL

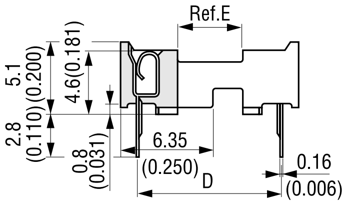
- Insulator : Glass-filled P.B.T. (UL94V-0)
- Contact material : Copper alloy
- Contact plating : 361T□-F ; Pure tin over Nickel
  361G; Gold over Nickel

Dimensions

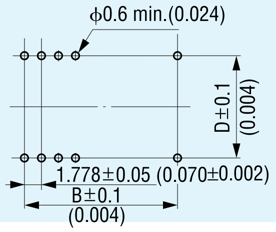
Unit:mm(inch)



Cross Section



PC Board Pattern



Packaging style
Pipe

Dimensions

No.of contacts	A	B	C	D	E	Number of packaging
28	25.17 (0.991)	23.114 (0.910)	12.65 (0.498)	10.16 (0.400)	4.22 (0.166)	20
40	35.84 (1.411)	33.782 (1.330)	17.73 (0.698)	15.24 (0.600)	9.30 (0.366)	14
42	37.62 (1.481)	35.56 (1.400)	17.73 (0.698)	15.24 (0.600)	9.30 (0.366)	13
56	50.07 (1.971)	48.006 (1.890)	17.73 (0.698)	15.24 (0.600)	9.30 (0.366)	10
64	57.18 (2.251)	55.118 (2,170)	21.54 (0.848)	19.05 (0.750)	12.25 (0.482)	8